Docket No.: GR 98 P 2661 D

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Manfred Engelhardt

Div. of Applic. No. : 09/816,923, filed March 23, 2001

Div. filed : August 22, 2003

Title : Method of Producing an Integrated Circuit Configuration

Examiner : Alexander O. Williams Group Art Unit: 2826

INFORMATION DISCLOSURE STATEMENT

Hon. Commissioner for Patents, Alexandria, VA 22313-1450

Sir:

In accordance with 37 C.F.R. 1.98, the following patents and/or publications are cited herewith:

U.S. Patent No. 5,308,793 (Taguchi et al.), dated May 3, 1994;

U.S. Patent No. 5,612,254 (Mu et al.), dated March 18, 1997;

Published European Patent Application No. EP 0 798 778 A2 (Inohara et al.), dated October 1, 1997;

International Search Report dated March 7, 2000;

International Preliminary Examination Report dated December 21, 2000.

The above-mentioned references were cited in an *Information Disclosure Statement* filed July 30, 2002, in parent application No. 09/816,923.

Published, European Patent Application No. EP 0 892 428 A2 (Nguyen et al.), dated January 20, 1999;

"A High Performance 3.97μm² CMOS SRAM Technology Using Self-Aligned Local Interconnect and Copper Interconnect Metallization" (Woo et al.), 1998 Symposium on VLSI Technology Digest of Technical Papers, pp. 12-13;

"A High-Performance Sub-0.25 μm CMOS Technology with Multiple Thresholds and Copper Interconnects" (Su et al.), 1998 Symposium on VLSI Technology Digest of Technical Papers, pp. 18-19.

The above-mentioned references were cited in an *Information Disclosure Statement* filed August 19, 2002, in parent application No. 09/816,923.

U.S. Patent No. 5,966,634 (Inohara et al.), dated October 12, 1999;

U.S. Patent No. 6,150,272 (Liu et al.), dated November 21, 2000.

The above-mentioned references were cited in an Office Action dated September 19, 2002, in parent application No. 09/816,923.

U.S. Patent No. 6,136,682 (Hegde et al.), dated October 24, 2000;

U.S. Patent No. 6,197,688 B1 (Simpson), dated March 6, 2001;

U.S. Patent No. 6,221,780 B1 (Greco et al.), dated April 24, 2001;

U.S. Patent No. 6,251,772 B1 (Brown), dated June 26, 2001;

U.S. Published Patent Application US 2002/0019131 A1 (Ohtsuka et al.), dated February 14, 2002;

U.S. Published Patent Application US 2002/0098673 A1 (Yeh et al.), dated July 25, 2002.

The above-mentioned references were cited in an Office Action dated April 4, 2003, in parent application No. 09/816,923.

U.S. Patent No. 6,472,304 B2 (Chittipeddi et al.), dated October 29, 2002

U.S. Published Patent Application US 2002/0005582 A1 (Nogami et al.), dated January 17, 2002;

U.S. Published Patent Application US 2002/0000665 A1 (Barr et al.), dated January 3, 2002.

The above-mentioned references were cited in an Office Action dated July 17, 2003, in parent application No. 09/816,923.

Respectfully submitted,

LAURENCE A. GREENBERG REG. NO. 29,308

For Applicants

Date:

August 22, 2003

Lerner and Greenberg, P.A. Post Office Box 2480 Hollywood, FL 33022-2480

Tel:

(954) 925-1100

Fax:

(954) 925-1101

/bb

FORM PTO-1449 (SUBSTITUTE) U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE				Attorney Docket No.: Divisional of Applic. No. GR 98 P 2661 P D 09/816,923 Applicant							
			Manfred Engelhardt								
		TION DISCLOSURE	Pilica Data (CDistributa) Comma Art Haif								
STATEMENT BY APPLICANT (37 CFR 1.98(b))				Filing Date of Divisional Group Art Unit August 22, 2003 2826							
	(- '										
EXAMINER INITIALS		PATENT NO.	DATE	PATENTEE	CLASS	SUB CLASS	FIL DA				
INITIALS	 A	5,308,793	05/94	Taguchi et al.	CLASS	CLASS	DA	12			
	В	5,612,254	03/97	Mu et al.							
	$\frac{1}{C}$	5,966,634	10/99	Inohara et al.							
				-							
	D	6,150,272	11/00	Liu et al.							
	Е	6,136,682	10/00	Hegde et al.							
	F	6,197,688 B1	03/01	Simpson	-						
	G	6,221,780 B1	04/01	Greco et al.							
	Н	6,251,772 B1	06/01	Brown							
	I	6,472,304 B2	10/02	Chittipeddi et al.							
		FOREI	GN PATE	NT DOCUMENT							
		DOCUMENT NO.	DATE	COUNTRY	CLASS	SUB CLASS	TRA: YES				
	J	EP 0 798 778 A2	10/97	Europe				İ			
	K	EP 0 892 428 A2	01/99	Europe							
	L										
	М										
	N										
0	THER	DOCUMENTS (Inc	cluding Au	ithor, Title, Date, Pe	rtinent Pag	ges, etc.)					
		"A High Performance 3.97μm² CMOS SRAM Technology Using Self-Aligned Local Interconnect and Copper Interconnect Metallization" (Woo et al.), 1998 Symposium on VLSI Technology Digest of Technical Papers, pp. 12-13.									
		"A High-Performance Sub-0.25 μm CMOS Technology with Multiple Thresholds and Copper Interconnects" (Su et al.), 1998 Symposium on VLSI Technology Digest of Technical Papers, pp. 18-19.									
EXAMINER				DATE CONSIDE	ERED						
				tot citation is in conford. Include copy of this							

FORM PTO-1449 (SUBSTITUTE)				Attorney Docket No.: Divisional of Applic. No. GR 98 P 2661 P D 09/816,923					
U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE INFORMATION DISCLOSURE				Applicant Manfred Engelhardt					
	TEME	NT BY APPLICANT CFR 1.98(b))	Filing Date of Divisional Group Art Unit August 22, 2003 2826						
EXAMINER INITIALS	T	PATENT NO.	DATE	PATENTEE	CLASS	SUB CLASS		ING TE	
INTIALS	A	US 2002/0098673	07/02	Yeh et al.	CLASS	CLASS		<u>IL</u>	
	В	US 2002/0005582 A1	01/02	Nogami et al.					
	С	US 2002/0000665 A1	01/02	Barr et al.					
	D	US 2002/0019131 A1	02/02	Ohtsuka et al.					
	Е								
	F								
	G								
	Н								
	I								
		FOREIG	GN PATE	NT DOCUMENT					
		DOCUMENT NO.	DATE	COUNTRY	CLASS	SUB CLASS	TRA YES		
	J	\		<u> </u>					
	K				<u> </u>				
	L							!	
	M			 					
	N			<u></u>	<u>L</u>				
O	THER	DOCUMENTS (Inc	luding Au	thor, Title, Date, Per	rtinent Pag	ges, etc.)			
							_		
EXAMINER	•	*		DATE CONSIDE	RED	<u>-</u>			
EXAMINER: I through citation to applicant.	nitial if if not ii	citation considered, we conformance and no	hether or not considered	ot citation is in conformation. Include copy of this	nance with form with	MPEP 609 next comm	; Draw unicati	line on	